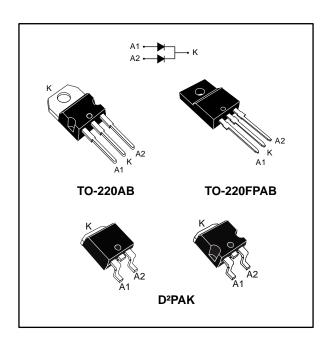


STPS20170C

High voltage power Schottky rectifier

Datasheet - production data



Description

Dual center tap Schottky rectifier diode suited for high frequency switched mode power supplies.

Table 1: Device summary

Symbol	Value
I _{F(AV)}	2 x 10 A
V _{RRM}	170 V
T _j (max.)	175 °C
V _F (typ.)	0.69 V

Features

- High reverse voltage
- High junction temperature capability
- Avalanche specification with derating curves
- Insulated package TO-220FPAB
 - Insulating voltage: 2000 V_{RMS} sine
- ECOPACK[®]2 compliant component for D²PAK on demand

Benefits

 Can challenge bipolar ultrafast diodes with better dynamic characteristics Characteristics STPS20170C

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol		Value	Unit			
V _{RRM}	Repetitive peak reverse	voltage			170	V
I _{F(RMS)}	Forward rms current				30	Α
		TO-220AB /	Tc = 155 °C	Per diode	10	
1	Average forward current δ = 0.5, square wave	D²PAK	Tc = 150 °C	Total	20	А
I _{F(AV)}		TO 000EDAD	T _C = 135 °C	Per diode	10	
		TO-220FPAB	Tc = 115 °C	Total	20	
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms}$ sinusoidal				180	Α
P _{ARM}	Repetitive peak avalanche power $ t_p = 10 \; \mu s, \\ T_j = 125 \; ^{\circ} C $			480	W	
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating jun	ction temperature	e ⁽¹⁾		175	

Notes:

Table 3: Thermal parameters

Symbol	Parameter			Max. value	Unit	
		TO-220AB / D²PAK	Per diode	2.2		
D	R _{th(j-c)} Junction to case	10-220AB / D-PAK	Total	1.3		
K th(j-c)		TO-220FPAB	Per diode	4.5	°C/W	
			Total	3.5	C/VV	
Б	Coupling	TO-220AB / D ² PAK		0.3		
R _{th(c)} Coupling	Coupling	TO-220FPAB		2.5		

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j \text{ (diode1)}} = P_{\text{(diode1)}} x R_{\text{th(j-c)}} \text{ (per diode)} + P_{\text{(diode2)}} x R_{\text{th(c)}}$

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j-a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$

STPS20170C Characteristics

Table 4: Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
1_ (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-		15	μΑ
IR ^(*)		T _j = 125 °C		-		15	mA
	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 10 A	-		0.90	
V (2)		T _j = 125 °C		-	0.69	0.75	V
VF(=)		T _j = 25 °C	I- 20 A	-		0.99	V
		T _j = 125 °C	I _F = 20 A	-	0.79	0.86	

Notes:

 $^{(1)}\text{Pulse}$ test: t_p = 5 ms, δ < 2%

 $^{(2)}\text{Pulse}$ test: t_p = 380 $\mu\text{s},\,\delta$ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.64 \text{ x } I_{F(AV)} + 0.011 \text{ x } I_{F^{2}(RMS)}$

Characteristics STPS20170C

1.1 Characteristics (curves)

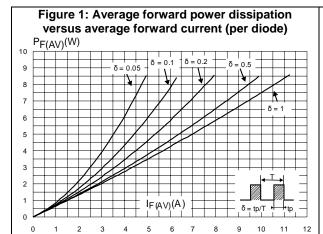


Figure 2: Average forward current versus ambient temperature (δ = 0.5, per diode) $I_{F(AV)}(A)$ $R_{th(j-a)} = R_{th(j-c)}$ (TO-220AB and D2PAK) 10 9 8 7 6 3 2 1 T_{amb} (°C) 0 0 75

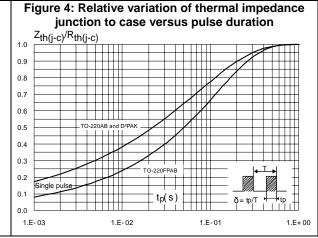
Figure 3: Normalized avalanche power derating versus pulse duration (T_j = 125 °C)

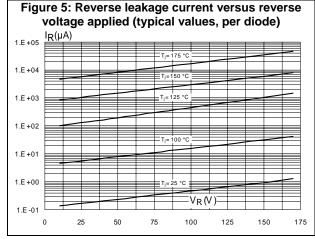
PARM(10 µs)

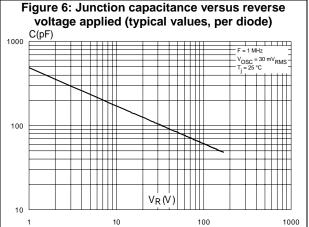
0.01

0.01

1 10 100 1000







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STPS20170C Characteristics

Figure 7: Forward voltage drop versus forward current (per diode)

100.0 IF (A)

100.0 TF 125 °C (maximum values) (maximum values) (maximum values) (maximum values)

0.1

Figure 8: Thermal resistance junction to ambient versus copper surface under tab for D²PAK Epoxy printed board FR4, e_{CU} = 35 μm S_{Cu}(cm²)



Package information STPS20170C

2 Package information

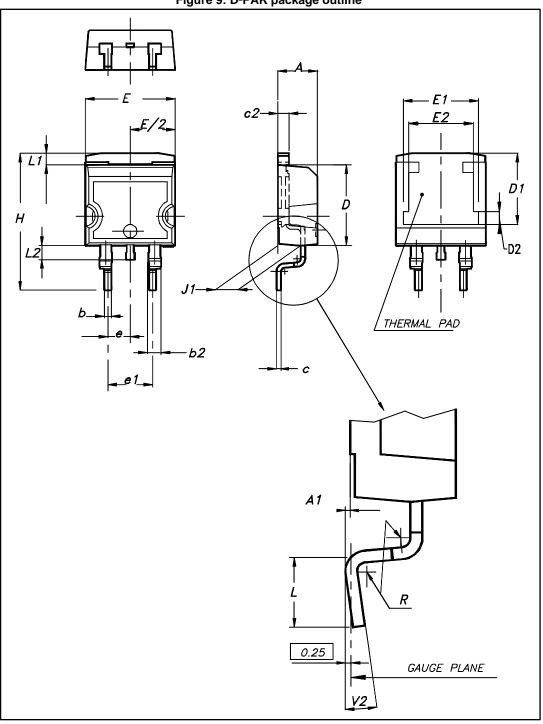
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB and TO-220FPAB)
- Maximum torque value: 0.7 N·m (for TO-220AB and TO-220FPAB)

STPS20170C Package information

2.1 D²PAK package information

Figure 9: D²PAK package outline

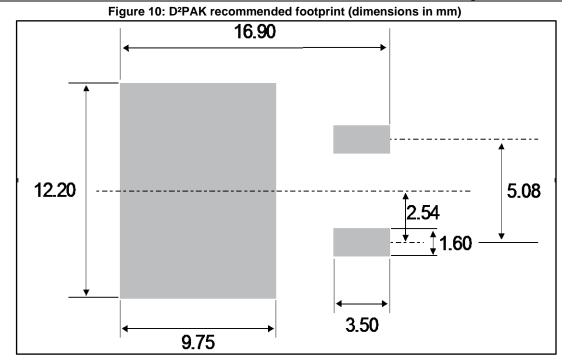


This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5: D2PAK package mechanical data

	Dimensions				
Ref.	Millimeters		Incl	hes	
	Min.	Max.	Min.	Max.	
Α	4.36	4.60	0.172	0.181	
A1	0.00	0.25	0.000	0.010	
b	0.70	0.93	0.028	0.037	
b2	1.14	1.70	0.045	0.067	
С	0.38	0.69	0.015	0.027	
c2	1.19	1.36	0.047	0.053	
D	8.60	9.35	0.339	0.368	
D1	6.90	8.00	0.272	0.311	
D2	1.10	1.50	0.043	0.060	
Е	10.00	10.55	0.394	0.415	
E1	8.10	8.90	0.319	0.346	
E2	6.85	7.25	0.266	0.282	
е	2.54	typ.	0.1	00	
e1	4.88	5.28	0.190	0.205	
Н	15.00	15.85	0.591	0.624	
J1	2.49	2.90	0.097	0.112	
L	1.90	2.79	0.075	0.110	
L1	1.27	1.65	0.049	0.065	
L2	1.30	1.78	0.050	0.070	
R	0.4	typ.	0.015		
V2	0°	8°	0°	8°	

STPS20170C Package information

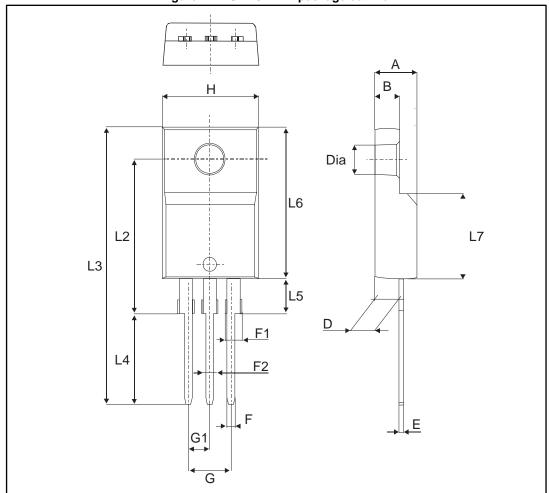




Package information STPS20170C

2.2 TO-220FPAB package information

Figure 11: TO-220FPAB package outline



STPS20170C Package information

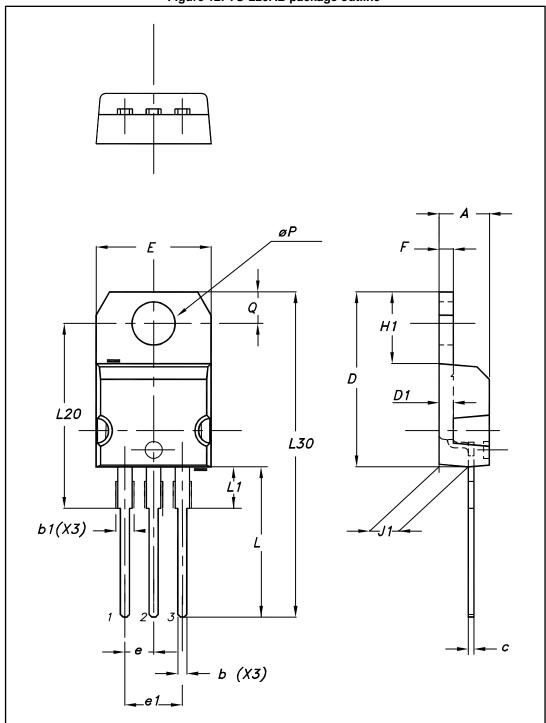
Table 6: TO-220FPAB package mechanical data

	Dimensions				
Ref.	Millim	neters	Inches		
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
В	2.5	2.7	0.098	0.106	
D	2.50	2.75	0.098	0.108	
E	0.45	0.70	0.018	0.027	
F	0.75	1.0	0.03	0.039	
F1	1.15	1.70	0.045	0.067	
F2	1.15	1.70	0.045	0.067	
G	4.95	5.20	0.195	0.205	
G1	2.40	2.70	0.094	0.106	
Н	10.00	10.40	0.393	0.409	
L2	16.00	typ.	0.63	typ.	
L3	28.60	30.60	1.126	1.205	
L4	9.80	10.6	0.386	0.417	
L5	2.90	3.60	0.114	0.142	
L6	15.90	16.40	0.626	0.646	
L7	9.00	9.30	0.354	0.366	
Dia	3.0	3.20	0.118	0.126	

Package information STPS20170C

2.3 TO-220AB package information

Figure 12: TO-220AB package outline



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Table 7: TO-220AB package mechanical data

		Dime	nsions	
Ref.	Millim	eters	Inc	hes
	Min.	Max.	Min.	Max.
А	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.70	0.045	0.067
С	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27	typ.	0.050	0 typ.
Е	10.00	10.40	0.394	0.409
е	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.640	6 typ.
L30	28.90	typ.	1.138	8 typ.
θР	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

Ordering information STPS20170C

3 Ordering information

Table 8: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS20170CT	STPS20170CT	TO-220AB	1.95 g	50	Tube
STPS20170CFP	STPS20170CFP	TO-220FPAB	1.7 g	50	Tube
STPS20170CG-TR	STPS20170CG	D²PAK	1.38 g	1000	Tape and reel

4 Revision history

Table 9: Document revision history

Date	Revision	Changes
Mar-2004	1	First issue.
28-Jul-2005	2	TO-220FPAB, I ² PAK and D ² PAK packages added.
14-Oct-2016	3	Removed I ² PAK package. Updated features and packages silhouettes in cover page. Updated Section 5: "Characteristics", Section 5.1: "Characteristics (curves)", Table 8: "Ordering information" and Section 6.2: "D ² PAK package information".

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